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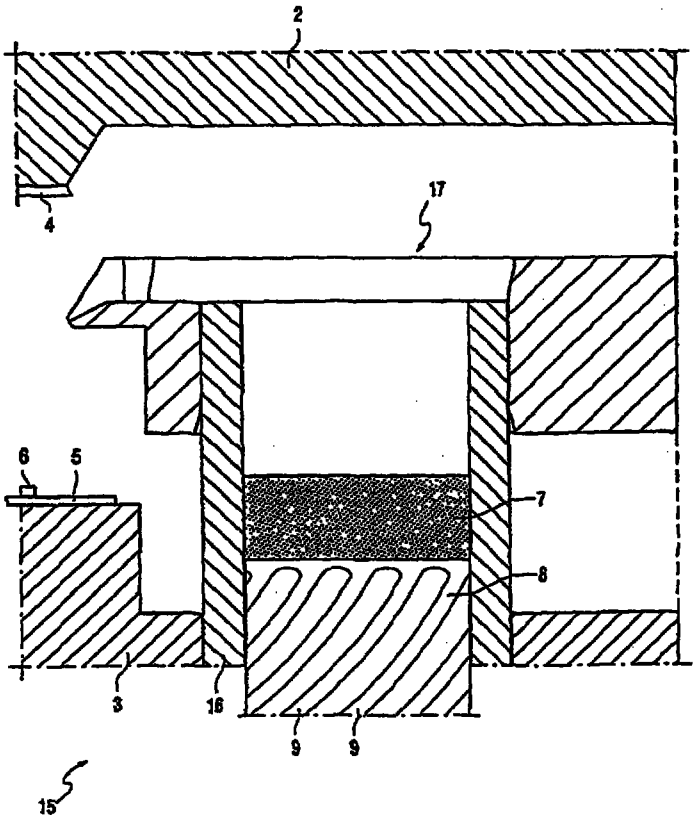
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(54) Title: DEVICE AND METHOD FOR ENCAPSULATING ELECTRONIC COMPONENTS MOUNTED ON A CARRIER



(57) Abstract: The invention relates to a device for encapsulating an electronic component, in particular a semiconductor, mounted on a carrier, comprising: an upper and a lower mould part, which mould parts are displaceable relative to each other between an encapsulating position in which the mould parts take a position enclosing at least one carrier between the mould parts and, connecting onto the enclosed carrier, defining at least one mould cavity, and an opened position in which the mould parts are situated at a greater mutual distance than in the encapsulating position, a holder member displaceable between the mould parts for urging at least an edge part of the carrier against one of the mould parts in the encapsulating position, and supply means for feeding liquid moulding material to the mould cavity. The invention also relates to a method for encapsulating an electronic component mounted on a carrier.

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